

## SILICON WAFERS

Addison Engineering stocks over 3-million silicon wafers (prime, reclaim, test) in diameters of 2", 3", 100mm, 125mm, 150mm, 200mm, and 300mm. We can accommodate small and large quantity requests with diverse specification requirements. Our prices are usually lower than test wafer prices from major prime producers. With over 20 years in the semiconductor industry, Addison's engineers can provide you with the level of support you need. Our specialty products include extra thick/thin wafers, silicon rings, soda lime, quartz (fused silica), Pyrex (borosilicate).

## WAFER PROCESSING

Addison Engineering has an extensive array of processing capabilities. On our silicon or yours, we can provide virtually any processing service you may need, from a simple oxide layer to completely patterned wafers. All of the services listed below are available, from developmental lots to full production runs. Our goal is to provide our customer with the highest quality processing at competitive pricing. Whether you are a fabless company, need a specific process infrequently, or just need some extra capacity, let our staff unburden your process engineers. We offer the following processes:

- Oxide: Thermal, TEOS/PETEOS, Gate, Low temp, PSG
- Silicon Nitride: LPCVD, low stress, ultra-low stress
- Polysilicon (undoped)
- Metal deposition: evaporation, sputter
- Epitaxial deposition
- Ion implantation
- SOI (oxidation, wafer bonding)
- Photolithography
- Photoresist: coat, strip
- Clean: RCA clean
- Ingot slicing
- Lapping & etch (Wafer thinning)
- Wafer downsize (diameter cut-down)
- Wafer dicing
- Wafer reclaim
- Laser marking
- Wafer bumping
- MEMS - Silicon machining

